



Attachment 2: Clean s t of claims as am nded

1. A method for packaging a microelectromechanical system (MEMS) device comprising:  
 using a partially-cured adhesive to attach a release sheet to a MEMS package flexible layer;  
 providing a cavity having a smooth surface perimeter and extending through the release sheet  
 and at least partially through the MEMS package flexible layer;  
 removing the release sheet; and  
 attaching the MEMS device to the MEMS package flexible layer with a MEMS structure of the  
 MEMS device being positioned within the cavity.

2. The method of claim 1 further comprising providing MEMS vias through the MEMS package  
 flexible layer and the cover extending to connection pads of the MEMS device and applying a MEMS  
 pattern of electrical conductors over the MEMS package flexible layer and the cover and extending  
 through the MEMS vias to the connection pads.

3. The method of claim 1 wherein using the adhesive to attach the release sheet to the MEMS  
 package flexible layer comprises coating the MEMS package flexible layer with the adhesive, partially  
 curing the adhesive, and then attaching the release sheet.

4. The method of claim 3 wherein attaching the MEMS device comprises using the adhesive

6. The method of claim 1, wherein the adhesive comprises a mixture of photodielectric and epoxy  
 materials.

7. A method for packaging a microelectromechanical system (MEMS) device comprising:  
 using a partially-cured adhesive to attach a release sheet to a MEMS package flexible layer;  
 providing a cavity extending through the release sheet and partially through the MEMS package  
 flexible layer;  
 providing a protective coating in the cavity;  
 then removing the release sheet; and  
 attaching the MEMS device to the MEMS package flexible layer with a MEMS structure of the  
 MEMS device being positioned within the cavity.

8. The method of claim 7 wherein the protective coating comprises a hermetic seal on the MEMS  
 package flexible layer.

16. A method for packaging a microelectromechanical system (MEMS) device comprising:  
 coating an MEMS package flexible layer with an adhesive;

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partially curing the adhesive;  
using the adhesive to attach a release sheet to the MEMS package flexible layer;  
providing a cavity having a smooth surface perimeter and extending through the release sheet, the adhesive, and at least partially through the MEMS package flexible layer;  
removing the release sheet;  
using the adhesive to attach the MEMS device to the MEMS package flexible layer with a MEMS structure of the MEMS device being positioned within the cavity;  
providing MEMS vias through the MEMS package flexible layer extending to connection pads of the MEMS device; and  
applying a MEMS pattern of electrical conductors on the MEMS package flexible layer and extending through the MEMS vias to the connection pads.

19. The method of claim 16 wherein providing the cavity comprises providing a cavity extending partially through the MEMS package flexible layer and further comprising, prior to removing the release sheet, providing a hermetic coating in the cavity.